1. All dimensions are in inches.
2. Material:
	1. Substrate: ROGERS 4003C, .008 thick
	2. Met1 and Met2: 0.5 oz. copper per layer
	3. Solder mask: Taiyo PSR-4000, top side only where indicated (Black)
	4. Silkscreen: White
3. Unless specified otherwise, tolerances are:
	1. PCB outline ± .002
	2. Position of internal cutout relative to hole pattern “A” (DIA=.070) is ± .002.
4. Burrs shall not exceed .002.
5. Copper is pulled back .002 on Met1 and Met2 from edge of PCB.
6. Met1 (top metal) features to be within .001 of CAD data base.
7. All vias to be located within ± .0015 of CAD data base.
8. Fabricate in accordance with IPC-6018B, per IPC-6011 Class 3.
9. Bag and tag parts separately.
10. All vias to be plated to .0007 min thickness.
11. Finished Met1 and Met2 Cu thickness to be .0014 ± .0008.
12. Maximum allowable negative feature .0008. Maximum allowable positive feature .0003
13. Drill Information
	1. DIA = .070 ± .0015, finished size, not plated (hole pattern A)
	2. DIA = .125 ± .003, finished size, not plated
	3. DIA = .096 ± .003, finished size, not plated
	4. DIA = .020 ± .003, drill size, Plated Thru
	5. DIA = .012 ± .003, drill size, Plated Thru
	6. DIA = .008 ± .003, drill size, Plated Thru
14. Plating:
	1. Met1 and Met2: Nickel Plate per QQ-N-290, Class 1, Grade G, 200 uin min (5 um min); Gold Plate per ASTM B 488, Type III, Grade A, 3-10 uin (0.08-0.25 um)
15. Hole Pattern “A” definition

